

HSF

NOTES:

- 1.Current Rating:2A Max (only one pin) ;
- 2.Voltage Rating:175V DC;
- 3.Contact Resistance:30mΩ Max;
- 4.Withstand Voltage:675V AC;
- 5.Insulation Resistance:5000MΩ Min;
- 6.Operating Temperature: -55°C to +125°C;
- 7.Insulator Material: LCP,G.F,UL94V-0,BK;
- 8.Contact Material:Copper Alloy;
- 9.Contact plating:
 Au on contact area (See ordering information),
 100μ" Matte TIN on solder area,
 50μ" Nickel underplating overall;
- 10.Recommended process:
 Wavesolder,Peak temperature:260±5°C, 5s ;

Ordering Information

37 2 0 X- S M XXX XXX XX X XX

OPTIONS

- 1=A
- 2=LC
- 3=FL

S=SOCKET

M=180° SMT

No OF POSITIONS

- 060=60PIN
- 120=120PIN
- 180=180PIN
- 240=240PIN
- 300=300PIN

LEAD STYLE

032=3.25

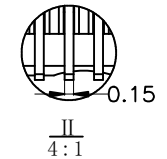
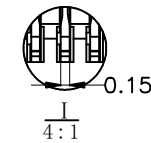
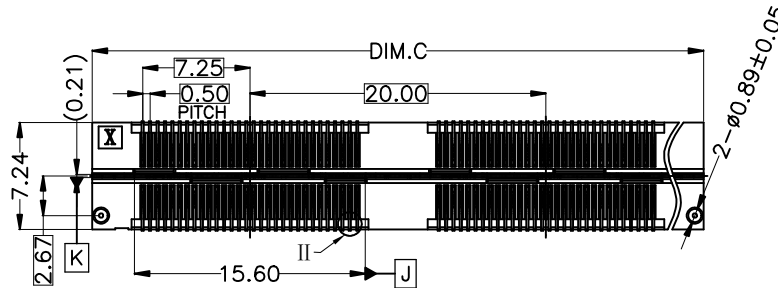
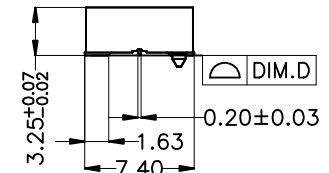
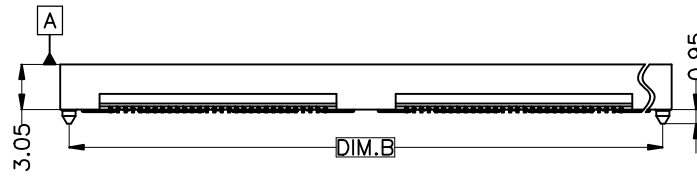
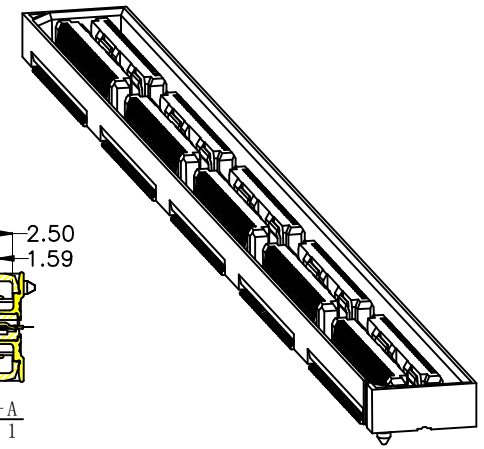
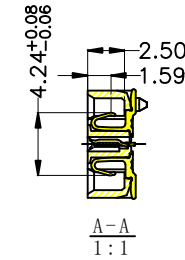
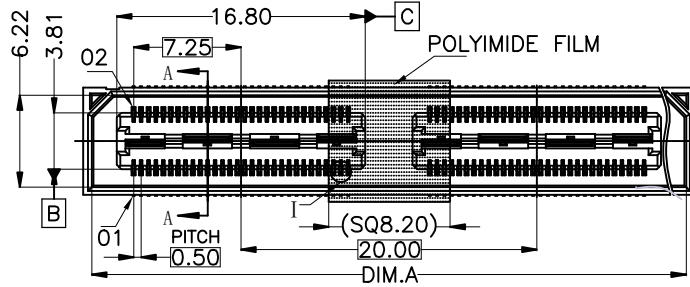
WCON INTERNAL CODE

PACKAGING

- A=VACUUM BOX
- R=TAPE&REEL

PLATING

- W1=SEL.3U"GOLD/MATTE SN
- W3=SEL.10U"GOLD/MATTE SN
- W5=SEL.30U"GOLD/MATTE SN



REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION	DRAW	DATE	SCALE	Fit	PART NO.
A0	2022.04.06	NEW		x.x ±0.40	Abt Chen	2022.04.06	UNIT	mm	RH-37203-SMXXX-032XXX11
				x.xx ±0.25	CHECK	DATE	SIZE	A4	TITE: - -
				x.xxx ±0.15	APPROVE	DATE	SHEET	1/4	0.5mmB0 TO B0 SOCKET SMT, H=3.25, ASSEMBLY
				Angle ± 3°			PROJ.		Customer NO.
				DIM TOL					



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